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EUROPEAN PATENT APPLICATION

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⑤④ **Activating a substrate for electroless plating.**

⑤⑦ A dielectric surface is conditioned for electroless plating of a conductive metal thereon by contacting the surface with a colloid of a precious metal and tin and then contacting the surface with a salt of ethylene diamine tetraacetic acid and/or diethylene triamine pentaacetic acid.



DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl. 4)
X	FR-A-2 439 214 (OXY METAL INDUSTRIES CORP.) * Page 9, lines 12,17; page 12, lines 18,22; page 7, line 14 *	1-10, 15,16	C 23 C 18/28
X	--- CHEMICAL ABSTRACTS, vol. 84, 1976, pages 588-589, abstract no. 188569d, Columbus, Ohio, US; & JP - A - 76 08 127 (HITACHI LTD.; HITACHI CHEMICAL CO., LTD.) 22-01-1976	1-10, 15,16	
A	--- US-A-3 011 920 (SHIPLEY) -----		
			TECHNICAL FIELDS SEARCHED (Int. Cl. 4)
			C 23 C H 05 K
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 23-06-1986	Examiner NGUYEN THE NGHIEP
CATEGORY OF CITED DOCUMENTS			
X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document	